



PARA LIGHT ELECTRONICS CO., LTD.
4F, No.1, Lane 93, Chien Yi Road, Chung Ho City, Taipei, Taiwan,
Tel: 886-2-2225-3733 Fax: 886-2-2225-4800
E-mail: para@para.com.tw <http://www.para.com.tw>

DATA SHEET

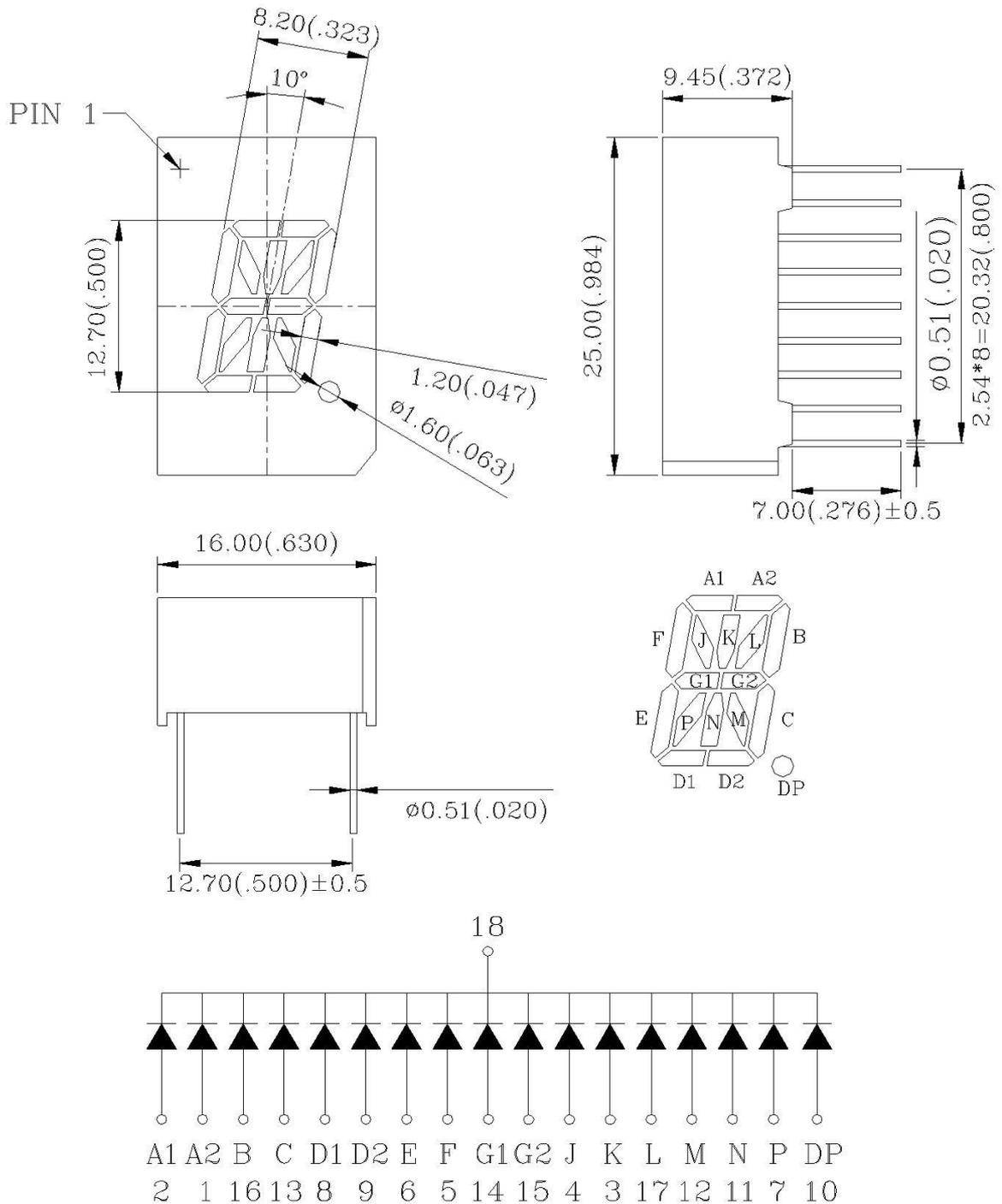
PART NO. : C-508I

REV : A / 0

CUSTOMER'S APPROVAL : _____

DCC : _____

PACKAGE DIMENSIONS



NOTES : 1. All dimensions are in millimeters. (inches)
 2. Tolerance is 6 0.25(0.010") unless otherwise specified.



0.50 INCH ALPHA-NUMERIC DIGIT DISPLAY

C-508I

REV:A / 0

FEATURES

- ∩ 12.70mm (0.50 inch) DIGIT HEIGHT
- ∩ COMMON CATHODE
- ∩ I.C. COMPATIBLE
- ∩ LOW POWER CONSUMPTION
- ∩ Pb FREE PRODUCTS ∩
- ROHS COMPLIANCE
- ∩ BLACK FACE, WHITE SEGMENTS

Raw Material : GaAlAs/GaAs

ABSOLUTE MAXIMUM RATING : (Ta = 25°C)

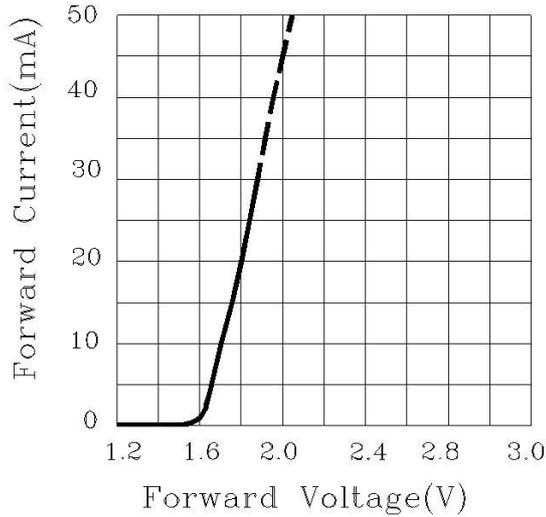
SYMBOL	PARAMETER	SUPER RED	UNIT
PD	Power Dissipation Per Segment	60	mW
VR	Reverse Voltage Per Segment	5	V
IAF	Continuous Forward Current Per Segment	20	mA
IPF	Peak Forward Current Per Segment (1/10 Duty Cycle,0.1ms Pulse Width)	100	mA
—	Derating Linear From 25°C Per Segment	0.4	mA/°C
Topr	Operating Temperature Range	-35°C to 85°C	
Tstg	Storage Temperature Range	-35°C to 85°C	

ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

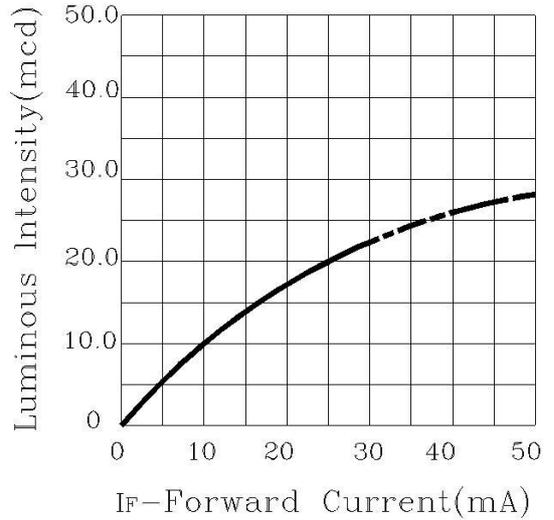
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage , Per Segment	IF = 20mA		1.8	2.2	V
IR	Reverse Current , Per Segment	VR = 5V			100	mA
IP	Peak Emission Wavelength	IF = 20mA		660		nm
ID	Dominant Wavelength	IF = 20mA		643		nm
Δl	Spectral Line Half—Width	IF = 20mA		20		nm
IV	Luminous Intensity Per Segment	IF = 10mA	4.0	10.0		mcd



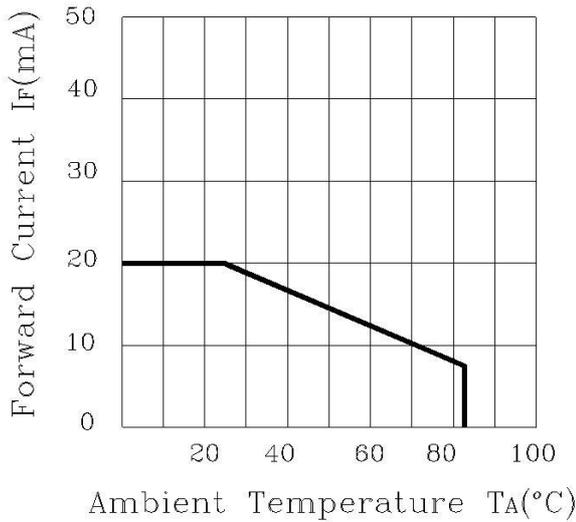
FORWARD CURRENT Vs. FORWARD VOLTAGE



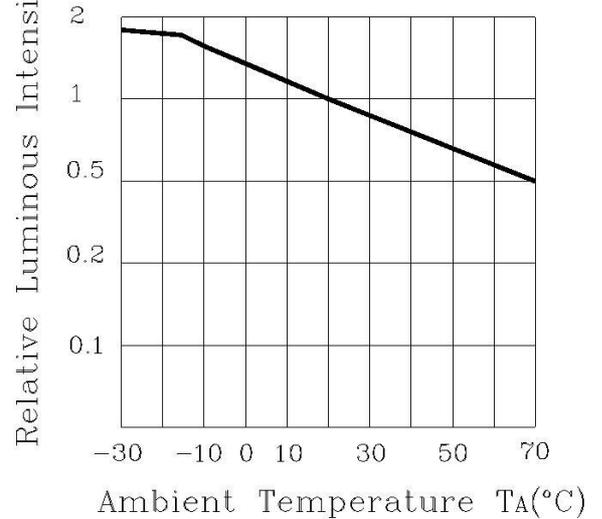
LUMINOUS INTENSITY Vs. FORWARD CURRENT



FORWARD CURRENT DERATING CURVE



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



SOLDERING

METHOD	SOLDERING CONDITIONS	REMARK
DIP SOLDERING	Bath temperature: 260 max Immersion time: within 5 sec	<input type="checkbox"/> Solder no closer than 2mm from the base of the package <input type="checkbox"/> Using soldering flux, "RESIN FLUX" is recommended.
SOLDERING IRON	Soldering iron: 30W or smaller Temperature at tip of iron: 260°C or lower Soldering time: within 5 sec.	<input type="checkbox"/> During soldering, take care not to press the tip of iron against the PIN. (To prevent heat from being transferred directly to the PIN.)

1) When soldering the PIN of Display in a jig that the package is fixed with a panel (See flg.1), be careful not to stress the PIN with iron tip. When soldering Display in a condition that the package is fixed with a panel, be careful not to cling and stress the surface of Display on the panel to avoid damaging the Display.

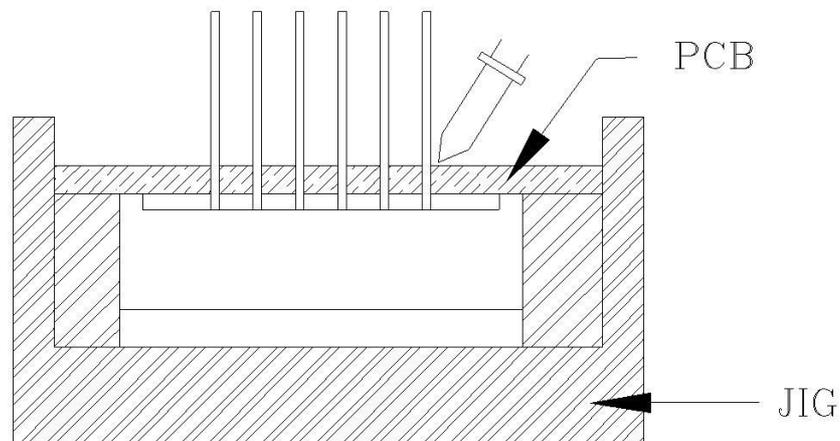


Fig.1

Regarding solution in the tinning oven for product-tinning, compound sub-solution made of tin & copper and silver is proposed with the temperature of Celsius 260. The proportion of the alloyed solution is tin 95.5: copper 3.5: silver 0.5 by percentage. The time of tinning is constantly 3 seconds.